

## PATENT ABSTRACTS OF JAPAN

(11)Publication number : 06-302572

(43)Date of publication of application : 28.10.1994

(51)Int.Cl.

H01L 21/304  
H01L 21/304  
H01L 21/66  
H01L 21/68  
H01L 21/78

(21)Application number : 05-084217

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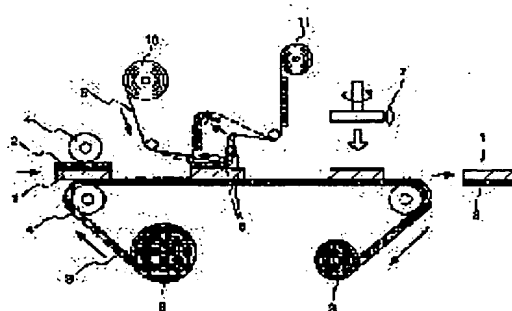
(22)Date of filing : 12.04.1993

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**(54) MANUFACTURE OF SEMICONDUCTOR DEVICE AND TAPE ADHERING AND PEELING APPARATUS****(57)Abstract:**

**PURPOSE:** To eliminate a crack of a wafer due to vibration and impact during conveying of the wafer, removal from a wafer cassette, etc., by grinding a rear surface of the wafer, then adhering a reinforcing tape to the rear surface of the wafer, and peeling a protective tape adhered to an element forming surface.

**CONSTITUTION:** A wafer 1 adhered with a protective tape 2 is inserted into an adhering roller 4, a reinforcing tape 3 fed from a reinforcing tape roll 8 is adhered to a rear surface of the wafer 1 by the roller 4. Then, a peeling tape 5 fed from a peeling tape roll 10 is adhered to the tape 2 by a peeling roller 6, the tape 5 is peeled from the wafer 1, and the tape 5 is wound by a peeling tape winding roll 11. Thereafter, the tape 3 is cut by a cutter 7 to match a shape of the wafer 1. Then, a residue of the tape 3 cut by the cutter 7 is wound by a reinforcing tape winding roll 9. Thus, the tape 3 is adhered to hold a strength of the wafer 1.

**LEGAL STATUS**

[Date of request for examination]

[Date of sending the examiner's decision of rejection]

[Kind of final disposal of application other than the examiner's decision of rejection or application converted registration]

[Date of final disposal for application]

[Patent number]

[Date of registration]

[Number of appeal against examiner's decision of rejection]

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[Date of requesting appeal against examiner's  
decision of rejection]

[Date of extinction of right]

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